

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2872428

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PAUL KWOK KEUNG HO	03/28/2014
WING LEUNG WONG	03/28/2014
RECEIVING PARTY DATA	
Name:	NANO AND ADVANCED MATERIALS INSTITUTE LIMITED
Street Address:	ROOM 3641-3649, THE HONG KONG JOCKEY CLUB ENTERPRISE CENTER
Internal Address:	THE HONG KONG UNIVERSITY OF SCIENCE AND TECHNOLOGY
City:	HONG KONG
State/Country:	HONG KONG
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14288397
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	eip@eip.hk
Correspondent Name:	EAGLE IP LTD
Address Line 1:	13/F BRIGHT WAY TOWER
Address Line 2:	33 MONG KOK ROAD, KOWLOON
Address Line 4:	HONG KONG, HONG KONG
NAME OF SUBMITTER:	JACQUELINE C. LUI
SIGNATURE:	/JACQUELINE C. LUI/
DATE SIGNED:	05/28/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, we,

HO, Paul Kwok Keung, a Hong Kong resident, located at Hong Kong, CHINA; and

WONG, Wing Leung, a Hong Kong resident, located at Hong Kong, CHINA; (hereinafter "Assignors"), made certain new and useful inventions and improvements (hereinafter "Inventions and Improvements") that have been documented in a specification entitled "New conductive and photosensitive polymers"; for which we have executed application for patent in the United States (hereinafter "Application"); filed on even date herewith;

AND WHEREAS, Nano and Advanced Material Institute Ltd., a limited company organized and existing under and by virtue of the laws of Hong Kong, and having an office and place of business at Room 3641-3649, The Hong Kong Jockey Club Enterprise Center, The Hong Kong University of Science and Technology, Clear Water Bay, Kowloon, Hong Kong (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said Inventions and Improvements and said Application and in and to the patent to be obtained therefrom;

NOW THEREFORE, to all whom it may concern, be it known that in consideration of One Dollar (USD 1.00), and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold, assigned, and transferred, and by these present do sell, assign and transfer unto said Assignee, its successors, legal representatives or assigns, the entire right, title and interest for all countries in and to all inventions disclosed in said Application, and in and to the said Application, all divisions, continuations or renewals thereof, all patents which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any country or countries foreign to the United States for patents on said Inventions and Improvements, including an assignment of all rights under the provisions of the International Convention, and all patents of any country or countries foreign to the United States which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue any and all United States Patents, and any official of any country or countries foreign to the United States, whose duty is to issue patents on applications as aforesaid, to issue any and all patents, for the said Inventions and Improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of said Assignee, its successors, legal representatives and assigns.

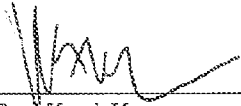
AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors, legal representatives and assigns all facts known to us relating to said Inventions and Improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors, legal representatives or assigns the entire right, title and interest in and to the said Inventions and Improvements, Application, patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore we covenant and agree with said Assignee, its successors, legal representatives or assigns, that no assignment, grant, mortgage license or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

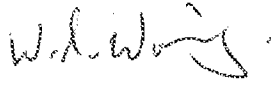
SIGNED this 28th day of March, 2014 in Hong Kong, China
_____ of _____ (month) _____ (year) _____ (city) _____ (country)

Assignor:

Assignor:




HO, Paul Kwok Keung
Rm 608-609, 6/F, Lake Side 2 10, Science Park West
Avenue Hong Kong Science Park Shatin, New
Territories, Hong Kong



WONG, Wing Leung
Rm 608-609, 6/F, Lake Side 2 10, Science Park West
Avenue Hong Kong Science Park Shatin, New
Territories, Hong Kong

Assignee:



Name Printed: YU Daniel
Title: CEO, Nano and Advanced Material Institute Ltd.